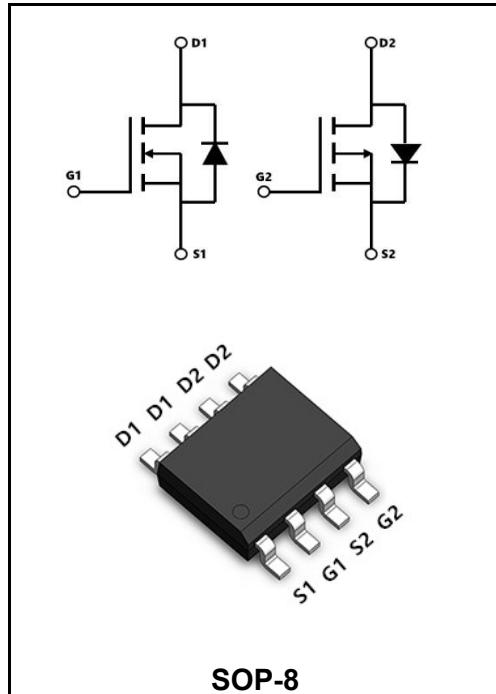


**40V N+P-Channel Enhancement Mode MOSFET**
**MAIN CHARACTERISTICS**

$I_D$	8.0A
$V_{DS}$	40V
$R_{DS(ON)-typ}(@V_{GS}=10V)$	<24mΩ(Typ:17 mΩ)
$R_{DS(ON)-typ}(@V_{GS}=4.5V)$	<35mΩ(Typ:25 mΩ)
$I_D$	-7.5A
$V_{DS}$	-40V
$R_{DS(ON)-typ}(@V_{GS}=-10V)$	<37.5mΩ(Typ:30 mΩ)
$R_{DS(ON)-typ}(@V_{GS}=-4.5V)$	<46mΩ(Typ:37 mΩ)


**DESCRIPTION**

The YFW4614S uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

**APPLICATION**

- ◆ Wireless charging
- ◆ Boost driver
- ◆ Brushless motor

**Absolute Maximum Ratings ( $T_c=25^\circ\text{C}$  unless otherwise noted)**

Characteristics	Symbols	Value		Units
		N-Ch	P-Ch	
Drain-Source Voltage	$V_{DS}$	40	-40	V
Gate - Source Voltage	$V_{GS}$	$\pm 20$	$\pm 20$	V
Continuous drain current@ 10V <sup>1</sup> , $T_A=25^\circ\text{C}$	$I_D$	8.0	-7.5	A
Continuous Drain Current, $V_{GS}$ @ 10V <sup>1</sup> , $T_A=70^\circ\text{C}$	$I_D$	5.2	-4.8	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	23	-22	A
Single Pulse Avalanche Energy <sup>3</sup>	$E_{AS}$	16.2	39	mJ
Avalanche Current	$I_{AS}$	18	-28	A
Total Power Dissipation <sup>4</sup> $T_A=25^\circ\text{C}$	$P_D$	2.6	2.6	W
Operating Junction Temperature Range	$T_J$	-55 to +150		°C
Storage Temperature Range	$T_{STG}$	-55 to +150		°C
Thermal Resistance Junction-Ambient <sup>1</sup>	$R_{\theta JA}$	105		°C/W
Thermal Resistance Junction-Case <sup>1</sup>	$R_{\theta JC}$	48		°C/W

**N-Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Parameter	Conditions	Symbol	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	$\mathbf{BV}_{DSS}$	40	---	---	<b>V</b>
BVDSS Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	$\Delta \mathbf{BV}_{DSS}/\Delta T_J$	---	0.034	---	<b>V/°C</b>
Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10\text{V}$ , $I_D=8\text{A}$	$R_{DS(\text{ON})}$	---	17	24	<b>mΩ</b>
	$V_{GS}=4.5\text{V}$ , $I_D=5\text{A}$		---	25	35	
Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250\mu\text{A}$	$V_{GS(\text{th})}$	1.0	1.5	2.5	<b>V</b>
$V_{GS(\text{th})}$ Temperature Coefficient		$\Delta V_{GS(\text{th})}$	---	-4.56	---	<b>mV/°C</b>
Drain-Source Leakage Current	$V_{DS}=32\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25^\circ\text{C}$	$I_{DSS}$	---	---	1	<b>uA</b>
	$V_{DS}=32\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=55^\circ\text{C}$		---	---	5	
Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$	$I_{GSS}$	---	---	$\pm 100$	<b>nA</b>
Forward Transconductance	$V_{DS}=5\text{V}$ , $I_D=5\text{A}$	$g_{fs}$	---	14	---	<b>S</b>
Gate Resistance	$V_{DS}=0\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	$R_g$	---	2.6	---	<b>Ω</b>
Total Gate Charge (4.5V)	$V_{DS}=20\text{V}$ $V_{GS}=4.5\text{V}$ $I_D=5\text{A}$	$Q_g$	---	5.5	---	<b>nC</b>
Gate-Source Charge		$Q_{gs}$	---	1.25	---	
Gate-Drain Charge		$Q_{gd}$	---	2.5	---	
Turn-On Delay Time	$V_{DD}=20\text{V}$ $V_{GS}=10\text{V}$ $R_G=3.3\Omega$ $I_D=1\text{A}$	$t_{d(on)}$	---	8.9	---	<b>ns</b>
Rise Time		$T_r$	---	2.2	---	
Turn-Off Delay Time		$t_{d(OFF)}$	---	41	---	
Fall Time		$t_f$	---	2.7	---	
Input Capacitance	$V_{DS}=15\text{V}$ $V_{GS}=0\text{V}$ $f=1\text{MHz}$	$C_{iss}$	---	593	---	<b>pF</b>
Output Capacitance		$C_{oss}$	---	76	---	
Reverse Transfer Capacitance		$C_{rss}$	---	56	---	
Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	$I_s$	---	---	8.0	<b>A</b>
Pulsed Source Current <sup>2,5</sup>		$I_{SM}$	---	---	23	<b>A</b>
Diode Forward Voltage <sup>2</sup>	$V_{GS}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	$V_{SD}$	---	---	1.2	<b>V</b>

Note :

- 1、The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3、The EAS data shows Max. rating . The test condition is  $V_{DD}=25\text{V}$ ,  $V_{GS}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{AS}=10\text{A}$
- 4、The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5、The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

**P-Electrical Characteristics (TJ=25°C, unless otherwise noted)**

Parameter	Conditions	Symbol	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	BV <sub>DSS</sub>	-40	---	---	V
BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =-1mA	△BV <sub>DSS</sub> /△T <sub>J</sub>	---	-0.02	---	V/°C
Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-8A	R <sub>DSS(ON)</sub>	---	30	37.5	mΩ
	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-5A		---	37	46	
Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250μA	V <sub>GS(th)</sub>	-1.0	-1.6	-2.5	V
V <sub>GS(th)</sub> Temperature Coefficient		△V <sub>GS(th)</sub>	---	3.72	---	mV/°C
Drain-Source Leakage Current	V <sub>DS</sub> =-32V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	I <sub>DSS</sub>	---	---	1	uA
	V <sub>DS</sub> =-32V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C		---	---	5	
Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	I <sub>GSS</sub>	---	---	±100	nA
Forward Transconductance	V <sub>DS</sub> =-5V, I <sub>D</sub> =-6A	g <sub>fs</sub>	---	13	---	S
Total Gate Charge (-4.5V)	V <sub>DS</sub> =-20V, V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-6A	Q <sub>g</sub>	---	11.5	---	nC
Gate-Source Charge		Q <sub>gs</sub>	---	3.5	---	
Gate-Drain Charge		Q <sub>gd</sub>	---	3.3	---	
Turn-On Delay Time	V <sub>DD</sub> =-15V, V <sub>GS</sub> =-10V, R <sub>G</sub> =3.3Ω, I <sub>D</sub> =-1A	t <sub>d(on)</sub>	---	22	---	ns
Rise Time		T <sub>r</sub>	---	15.7	---	
Turn-Off Delay Time		t <sub>d(OFF)</sub>	---	59	---	
Fall Time		t <sub>f</sub>	---	5.5	---	
Input Capacitance	V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V, f=1MHz	C <sub>iss</sub>	---	1243	---	pF
Output Capacitance		C <sub>oss</sub>	---	97	---	
Reverse Transfer Capacitance		C <sub>rss</sub>	---	80	---	
Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	I <sub>s</sub>	---	---	-7.5	A
Pulsed Source Current <sup>2,5</sup>		I <sub>SM</sub>	---	---	-22	A
Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>s</sub> =-1A, T <sub>J</sub> =25°C	V <sub>SD</sub>	---	---	-1.2	V

**Note :**

- 1、The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3、The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=-25V,V<sub>GS</sub>=-10V,L=0.1mH,I<sub>AS</sub>=-10A
- 4、The power dissipation is limited by 150°C junction temperature
- 5、The data is theoretically the same as I<sub>D</sub> and IDM , in real applications , should be limited by total power dissipation.

### N-Channel Typical Characteristics

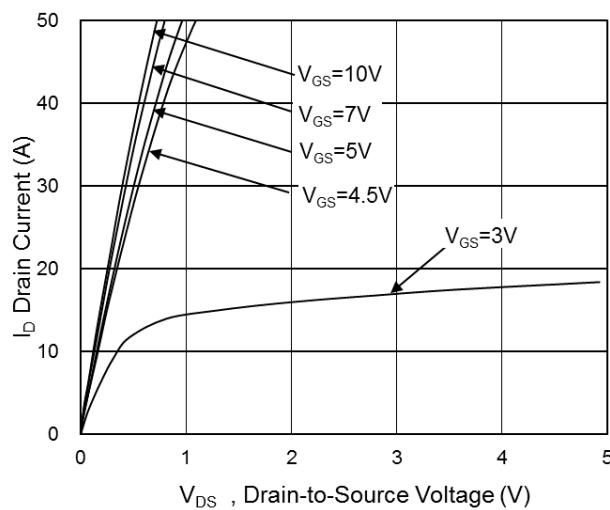


Fig.1 Typical Output Characteristics

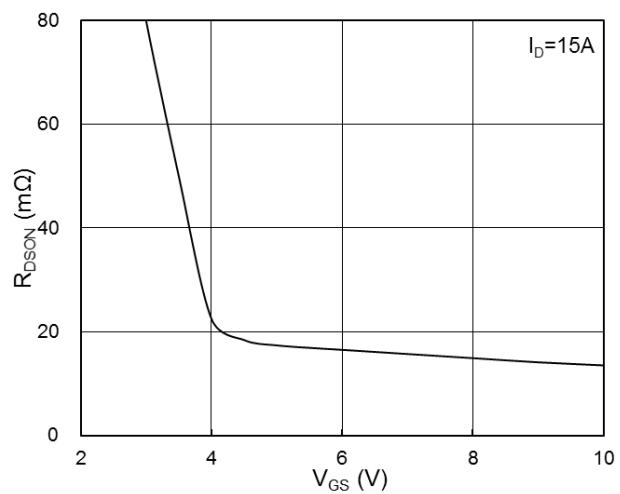


Fig.2 On-Resistance vs. G-S Voltage

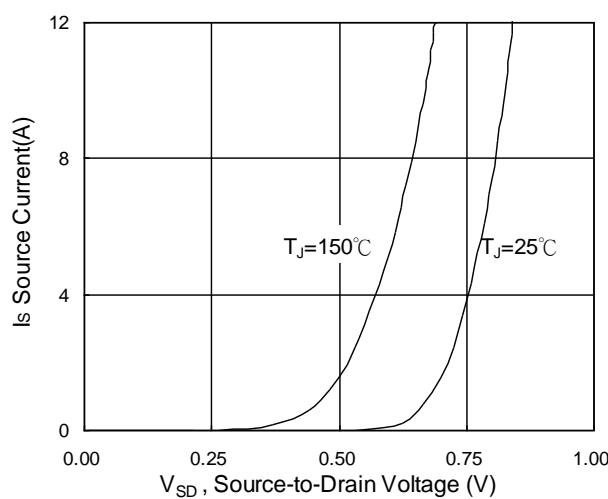


Fig.3 Forward Characteristics of Reverse

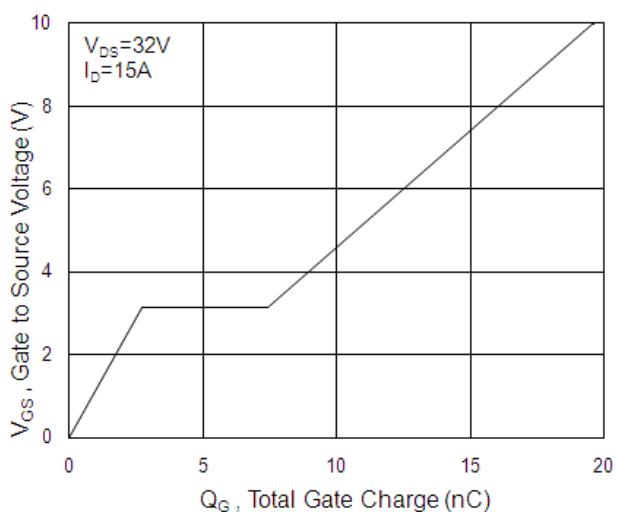


Fig.4 Gate-Charge Characteristics

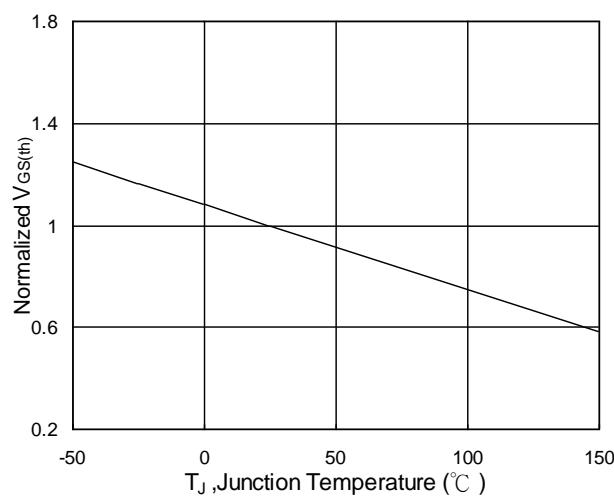


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

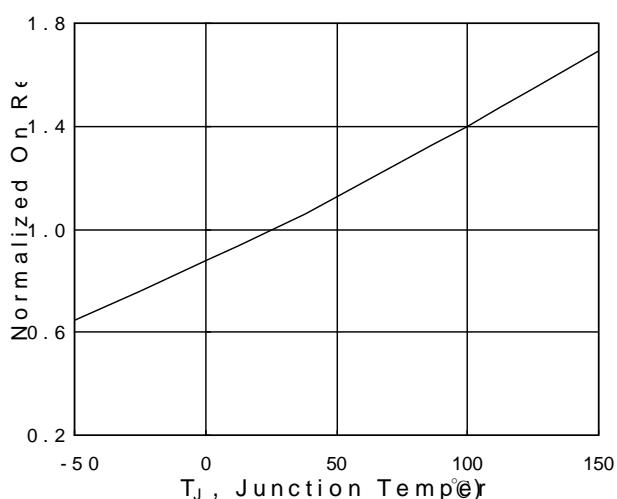
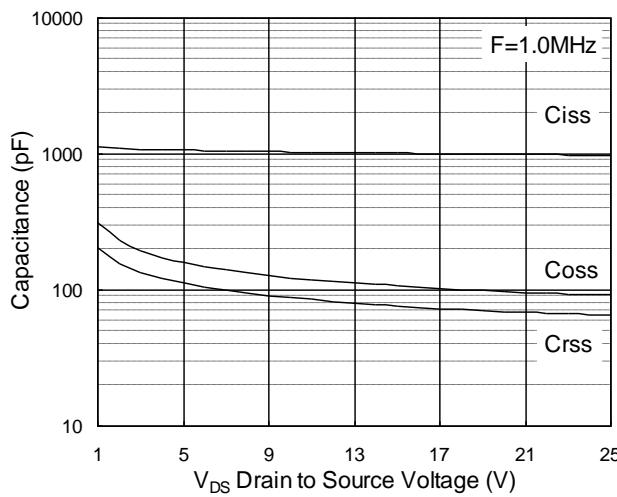
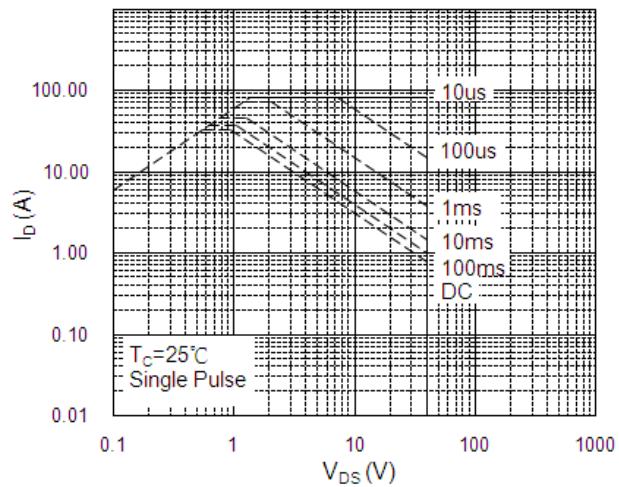


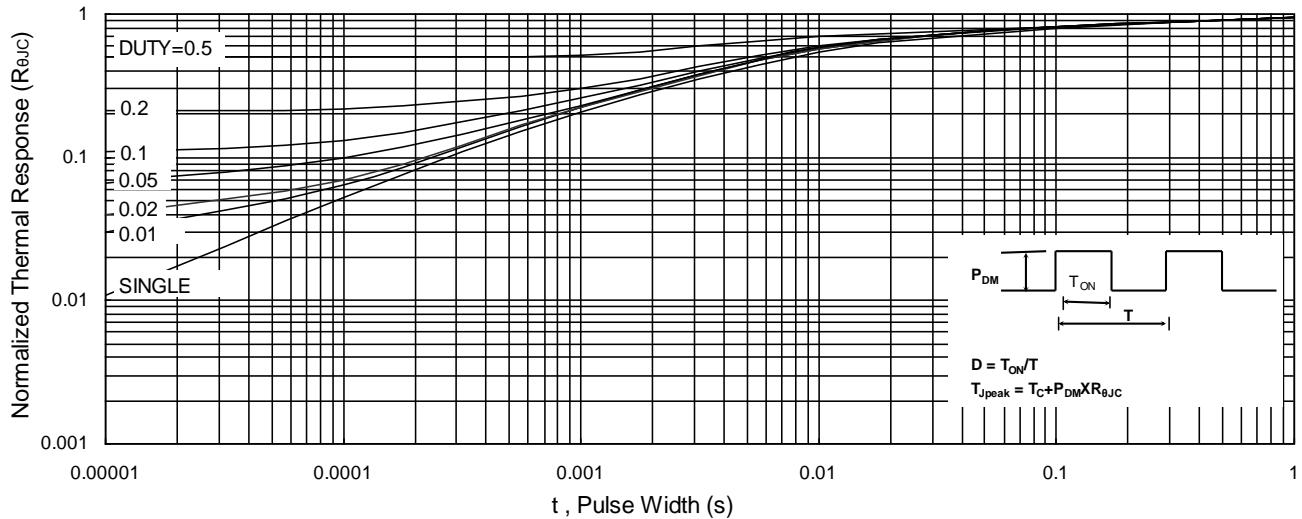
Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$



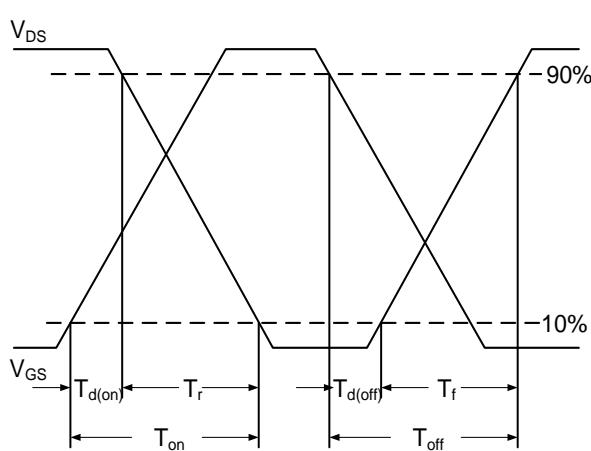
**Fig.7 Capacitance**



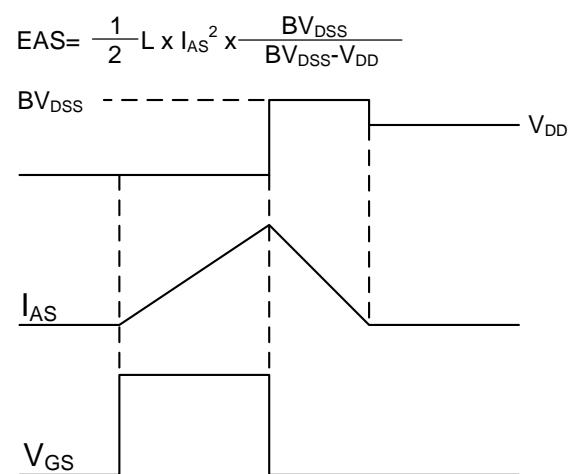
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**

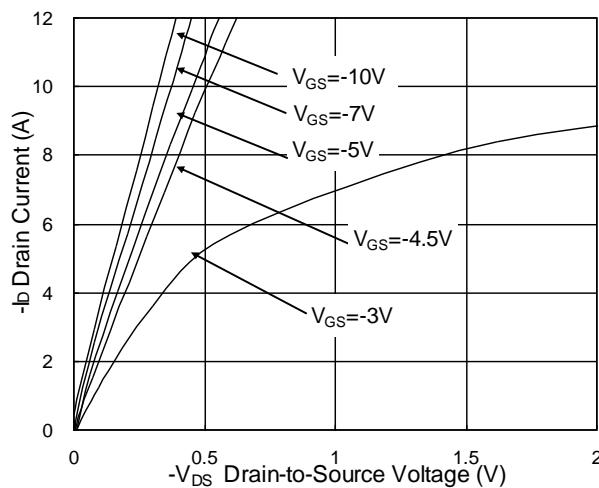


**Fig.10 Switching Time Waveform**

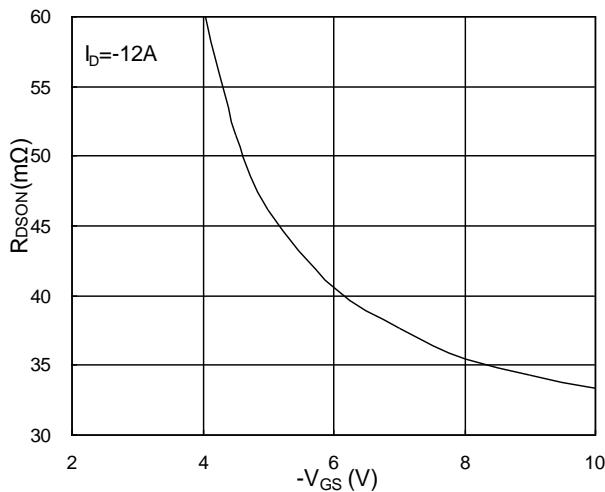


**Fig.11 Unclamped Inductive Switching Waveform**

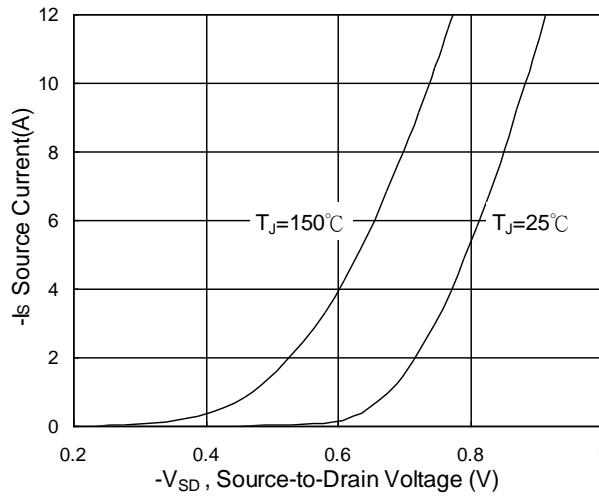
**P-Channel Typical Characteristics**



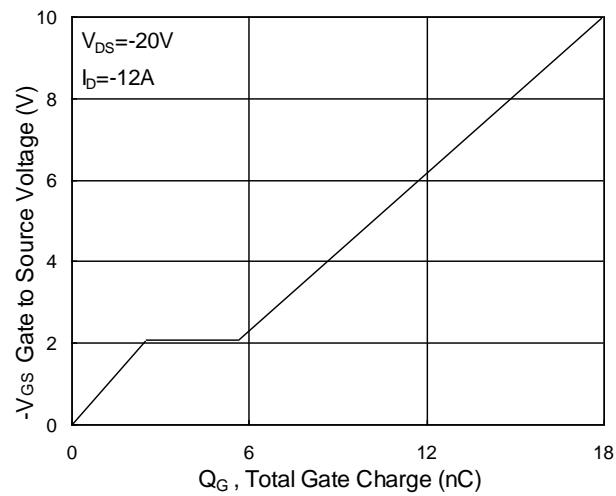
**Fig.1 Typical Output Characteristics**



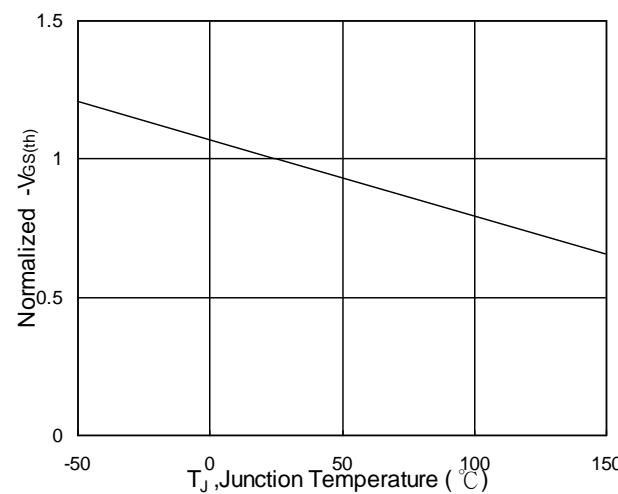
**Fig.2 On-Resistance v.s Gate-Source**



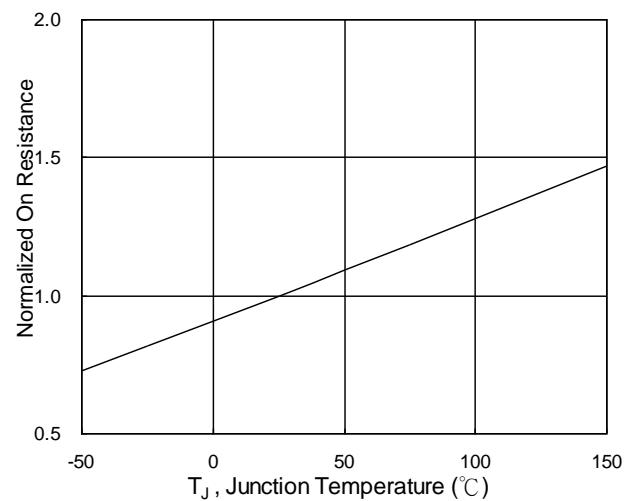
**Fig.3 Forward Characteristics of Reverse**



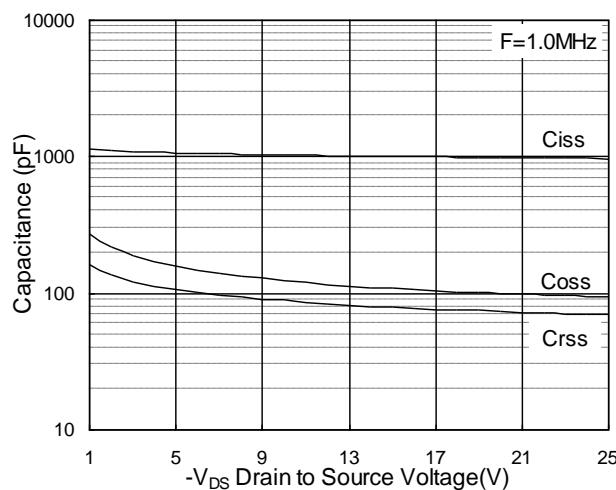
**Fig.4 Gate-Charge Characteristics**



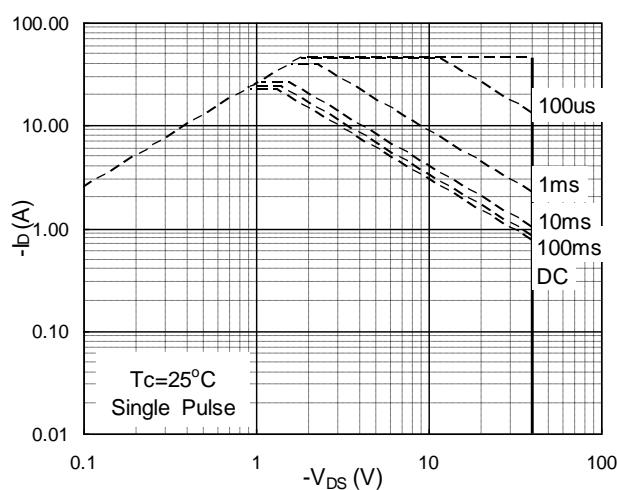
**Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$**



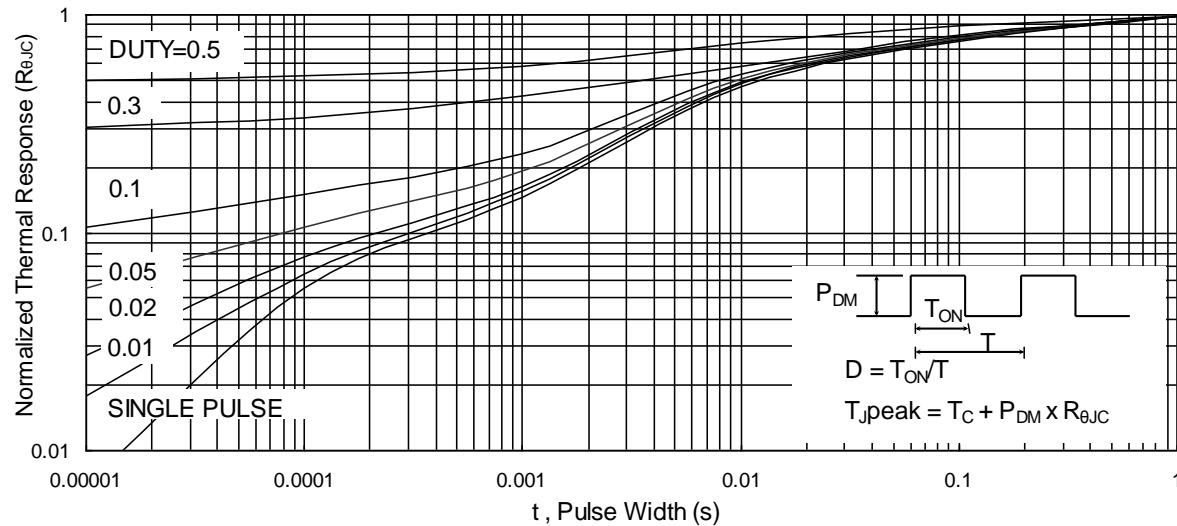
**Fig.6 Normalized  $R_{DS(on)}$  v.s  $T_J$**



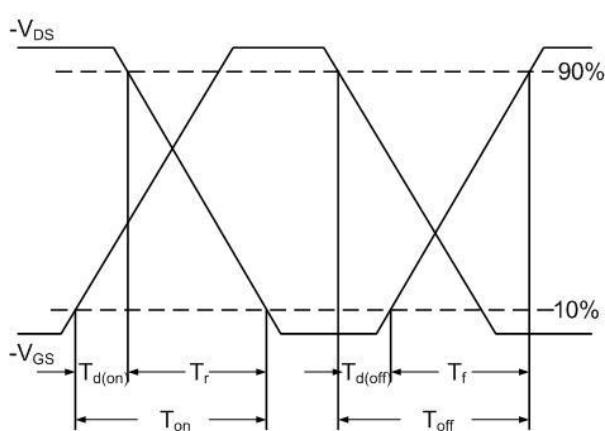
**Fig.7 Capacitance**



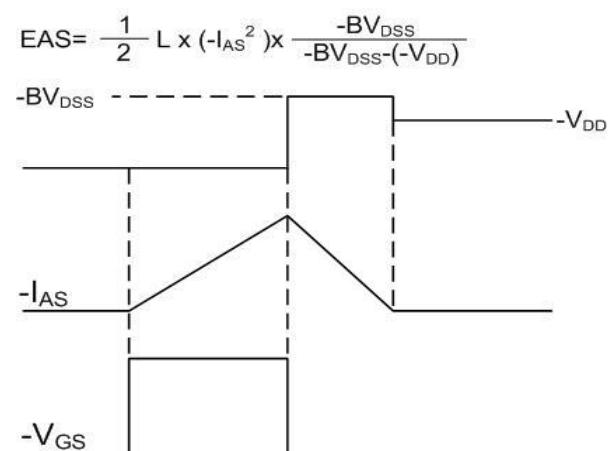
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**

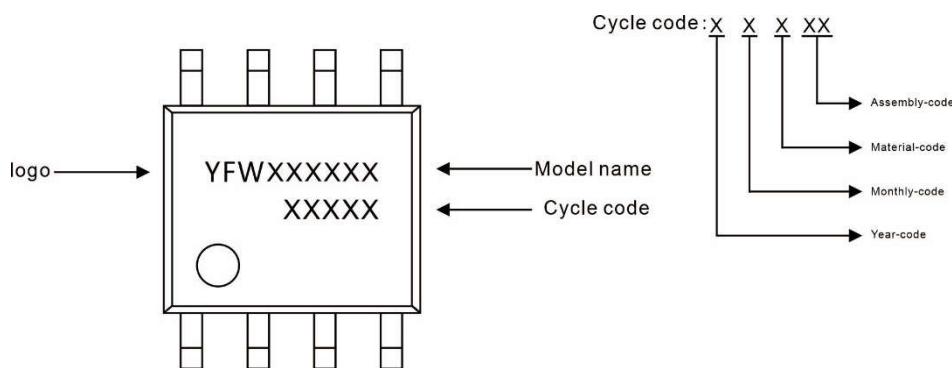


**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Waveform**

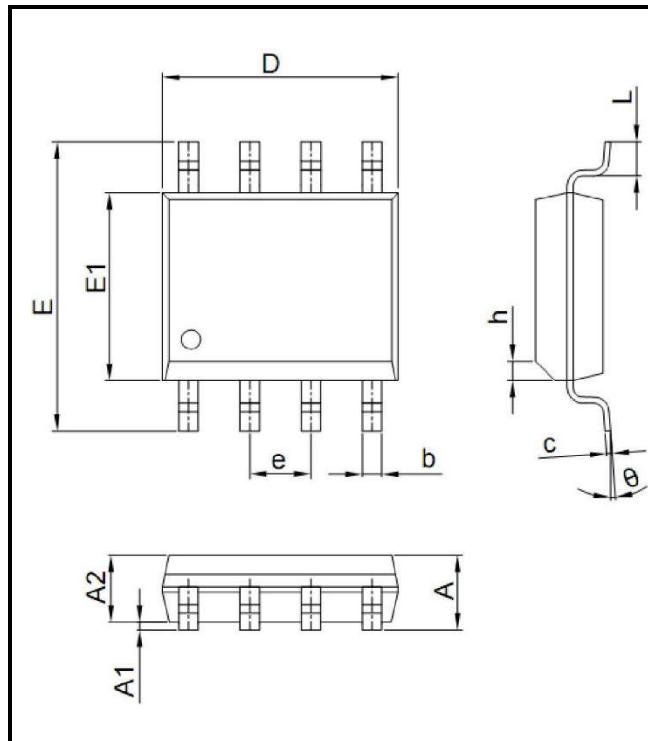
### Marking Diagram



### Ordering information

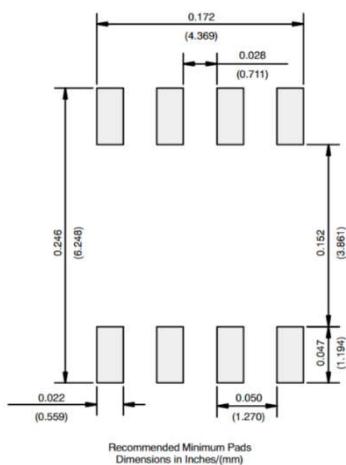
Package	Packing Description	Packing Quantity
SOP-8	Tape/Reel,13"reel	3000PCS/Reel 30000PCS/Carton

### Package Dimensions

**SOP-8**


Dim	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	1.35	1.75	0.053	0.069
A1	0.10	0.25	0.004	0.010
A2	1.35	1.50	0.053	0.059
b	0.35	0.55	0.014	0.022
c	0.15	0.25	0.006	0.010
D	4.80	5.00	0.189	0.197
D1	3.10	3.50	0.122	0.138
E	5.80	6.20	0.228	0.244
E1	3.80	4.00	0.150	0.157
E2	2.20	2.60	0.087	0.102
e	1.27 (BSC)		0.050 (BSC)	
L	0.40	1.27	0.016	0.050
θ	0°	8°	0°	8°

### The recommended mounting pad size



## Disclaimer

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